Characteristics T1235H, T1250H

#### 1 Characteristics

Table 2. Absolute maximum ratings

Symbol	Parame	Value	Unit			
	On-state rms current (full sine wave)	D <sup>2</sup> PAK, TO-220AB	T <sub>c</sub> = 130 °C	12	А	
IT(RMS)		TO-220AB Ins	T <sub>c</sub> = 120 °C	12		
	Non repetitive surge peak on-state current (full cycle, T <sub>j</sub> initial = 25 °C)	F = 50 Hz	t = 20 ms	120	А	
I <sub>TSM</sub>		F = 60 Hz	t = 16.7 ms	126		
l <sup>2</sup> t	I <sup>2</sup> t Value for fusing	t <sub>p</sub> = 10 ms		95	A <sup>2</sup> s	
dI/dt	Critical rate of rise of on-state current $I_G = 2 \times I_{GT}$ , $t_r \le 100 \text{ ns}$	F = 120 Hz	T <sub>j</sub> = 150 °C	50	A/µs	
V <sub>DSM</sub> /V <sub>RSM</sub>	Non repetitive surge peak off-state voltage	t <sub>p</sub> = 10 ms	T <sub>j</sub> = 25 °C	V <sub>DRM</sub> /V <sub>RRM</sub> + 100	V	
I <sub>GM</sub>	Peak gate current	t <sub>p</sub> = 20 μs	T <sub>j</sub> = 150 °C	4	Α	
P <sub>G(AV)</sub>	Average gate power dissipation $T_j = 150 ^{\circ}\text{C}$			1	W	
T <sub>stg</sub> T <sub>j</sub>	Storage junction temperature range Operating junction temperature range			- 40 to + 150 - 40 to + 150	°C	

Table 3. Electrical characteristics ( $T_j = 25$  °C, unless otherwise specified)

Symbol	Test conditions	Quadrant		Va	lue	Unit
Symbol	rest continions	Quadrant		T1235H	T1250H	
I <sub>GT</sub> <sup>(1)</sup>	$V_D = 12 \text{ V}, R_1 = 33 \Omega$	1 - 11 - 111	MAX.	35	50	mA
V <sub>GT</sub>	VD = 12 v, 11 = 00 s2	1 - 11 - 111	MAX.	1.0		<b>V</b>
$V_{GD}$	$V_D = V_{DRM}, R_L = 3.3 \text{ k}\Omega$ I - II - III		MIN.	0.15		<b>V</b>
I <sub>H</sub> <sup>(2)</sup>	I <sub>T</sub> = 500 mA		MAX.	35	75	mA
IL	I <sub>G</sub> = 1.2 I <sub>GT</sub>	I - III	MAX.	50	90	- mA
'L		II		80	110	
dV/dt (2)	$V_D = 67\% V_{DRM,}$ gate open, $T_j = 150 ^{\circ}\text{C}$		MIN.	1000	1500	V/µs
(dl/dt)c (2)	Without snubber, T <sub>j</sub> = 150 °C		MIN.	16	21	A/ms

<sup>1.</sup> minimum  $I_{\mbox{\scriptsize GT}}$  is guaranted at 20% of  $I_{\mbox{\scriptsize GT}}$  max.

<sup>2.</sup> for both polarities of A2 referenced to A1.

T1235H, T1250H Characteristics

Table 4. Static characteristics

Symbol	Test conditions				Unit
V <sub>T</sub> <sup>(1)</sup>	I <sub>TM</sub> = 17 A, t <sub>p</sub> = 380 μs	T <sub>j</sub> = 25 °C	MAX.	1.5	V
V <sub>t0</sub> (1)	Threshold voltage	T <sub>j</sub> = 150 °C	MAX.	0.80	V
R <sub>d</sub> <sup>(1)</sup>	Dynamic resistance	T <sub>j</sub> = 150 °C	MAX.	30	mΩ
I <sub>DRM</sub> I <sub>RRM</sub> <sup>(2)</sup>	$V_{DRM} = V_{RRM}$	T <sub>j</sub> = 25 °C	MAX.	5	μΑ
		T <sub>j</sub> = 150 °C	MAX.	3.9	
	V <sub>D</sub> /V <sub>R</sub> = 400 V (at peak mains voltage)	T <sub>j</sub> = 150 °C	MAX.	3.2	mA
	V <sub>D</sub> /V <sub>R</sub> = 200 V (at peak mains voltage)	T <sub>j</sub> = 150 °C	MAX.	2.7	

<sup>1.</sup> for both polarities of A2 referenced to A1

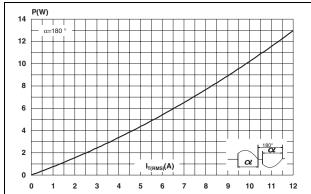
Table 5. Thermal resistance

Symbol	Parameter			Value	Unit
D	Junction to case (AC)		D <sup>2</sup> PAK / TO-220AB	1.4	
R <sub>th(j-c)</sub>			TO-220AB Ins	3.3	°C/W
R <sub>th(j-a)</sub>	Junction to ambient	$S = 1 \text{ cm}^2$	D <sup>2</sup> PAK	45	C/VV
	Junction to ambient		TO-220AB / TO-220AB Ins	60	

<sup>2.</sup>  $t_p = 380 \ \mu s$ 

Characteristics T1235H, T1250H

Figure 1. Maximum power dissipation versus Figure 2. On-state rms current versus case on-state rms current (full cycle) temperature (full cycle)



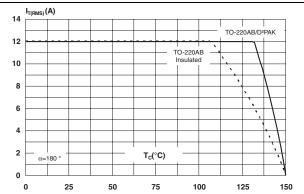
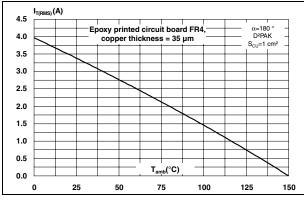


Figure 3. On-state rms current versus ambient temperature

Figure 4. Variation of thermal impedance versus pulse duration



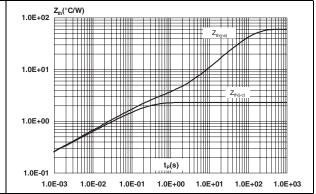
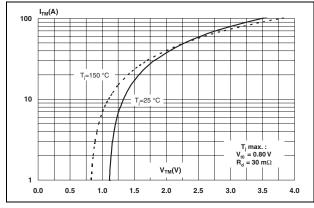
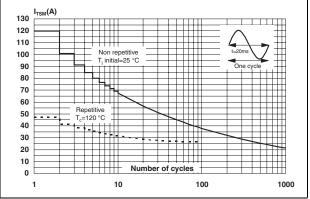


Figure 5. On-state characteristics (maximum values)

Figure 6. Surge peak on-state current versus number of cycles

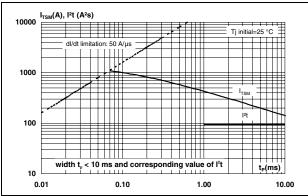




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T1235H, T1250H Characteristics

Figure 7. Non-repetitive surge peak on-state current for a sinusoidal pulse with sinuso



2.5 | I<sub>GT</sub>, I<sub>I<sub>I</sub>P</sub>, I<sub>L</sub> [T<sub>j</sub>] / I<sub>GT</sub>, I<sub>I<sub>I</sub>P</sub>, I<sub>L</sub> [T<sub>j</sub>=25°C] | 2.0 | I<sub>GT</sub> | I<sub>I</sub>R I<sub>L</sub> | I<sub>I</sub>R I<sub>I</sub> | I<sub>I</sub>R I<sub>L</sub> | I<sub>I</sub>R I<sub>L</sub> | I<sub>I</sub>R I<sub>L</sub> | I<sub>I</sub>R I<sub>L</sub> | I<sub>I</sub>R I<sub>I</sub> | I<sub>I</sub>R I<sub>L</sub> | I<sub>I</sub>R I<sub>I</sub> | I<sub>I</sub>R I<sub>I</sub>R I<sub>I</sub> | I<sub>I</sub>R I<sub>I</sub>R I<sub>I</sub> | I<sub>I</sub>R I<sub>I</sub>R I<sub>I</sub> | I<sub>I</sub>

Figure 9. Relative variation of critical rate of Figure 10. decrease of main current (dl/dt)c versus reapplied (dV/dt)c

Figure 10. Relative variation of critical rate of decrease of main current versus junction temperature

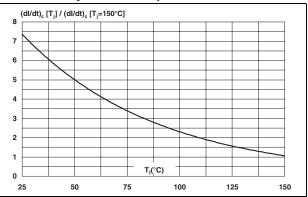


Figure 11. Leakage current versus junction temperature for different values of blocking voltage (typical values)

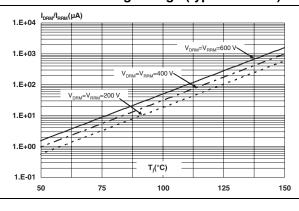
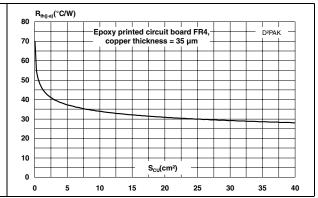
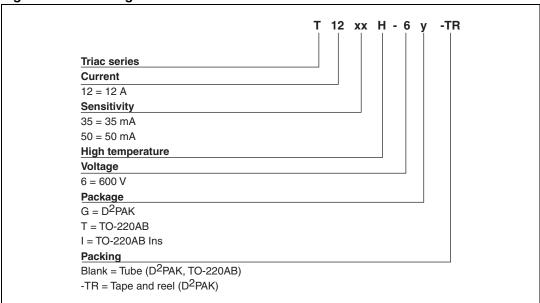


Figure 12. Variation of thermal resistance junction to ambient versus copper surface under tab



## 2 Ordering information scheme

Figure 13. Ordering information scheme



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T1235H, T1250H Package information

#### 3 Package information

- Epoxy meets UL94, V0
- Recommended torque 0.4 to 0.6 N⋅m

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <a href="https://www.st.com">www.st.com</a>. ECOPACK<sup>®</sup> is an ST trademark.

Table 6. D<sup>2</sup>PAK dimensions

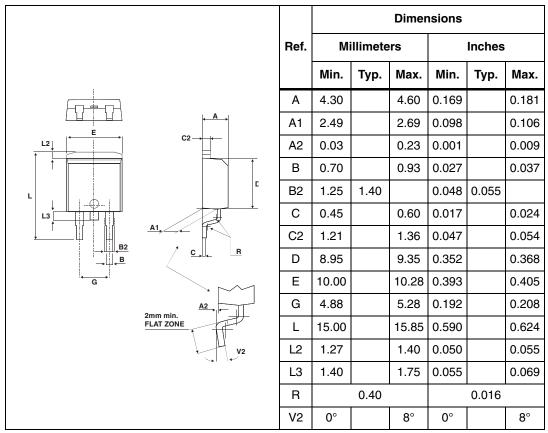
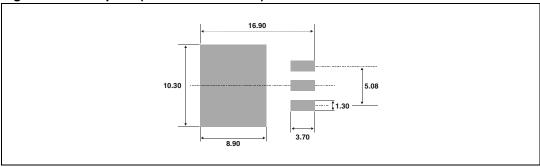


Figure 14. Footprint (dimensions in mm)

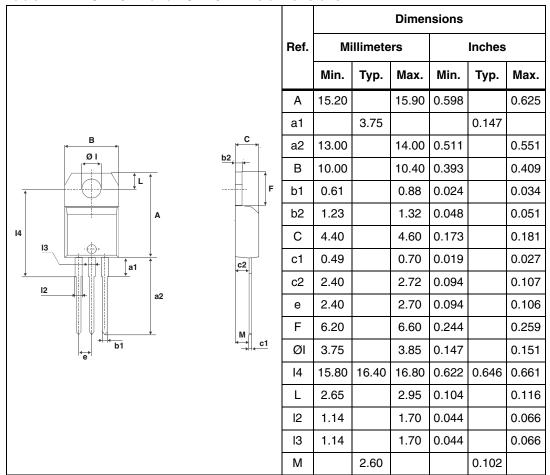


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Table 7. TO-220AB and TO-220AB Ins dimensions



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# 4 Ordering information

Table 8. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
T12xxH-6G	T12xxH 6G	D <sup>2</sup> PAK	1.5 g	50	Tube
T12xxH-6G-TR	T12xxH 6G	D <sup>2</sup> PAK	1.5 g	1000	Tape and reel
T12xxH-6T	T12xxH 6T	TO-220AB	2.3 g	50	Tube
T12xxH-6l	T12xxH 6l	TO-220AB Ins	2.3 g	50	Tube

## 5 Revision history

Table 9. Document revision history

Date	Revision	Changes	
17-Apr-2007	1	First issue.	
20-Sep-2011	2	Updated: Features, Description and Figure 2.	

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